



Welcome to [E-XFL.COM](https://www.e-xfl.com)

Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

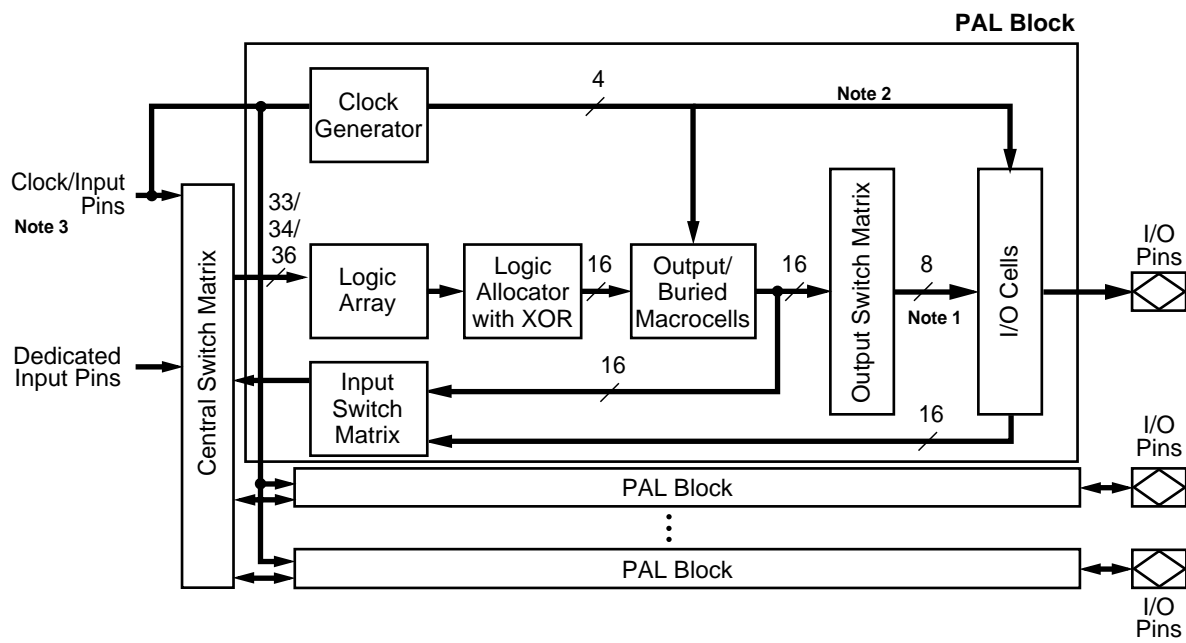
Details

Product Status	Not For New Designs
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	-
Number of Macrocells	256
Number of Gates	-
Number of I/O	128
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m4a5-256-128-10ync

FUNCTIONAL DESCRIPTION

The fundamental architecture of ispMACH 4A devices (Figure 1) consists of multiple, optimized PAL[®] blocks interconnected by a central switch matrix. The central switch matrix allows communication between PAL blocks and routes inputs to the PAL blocks. Together, the PAL blocks and central switch matrix allow the logic designer to create large designs in a single device instead of having to use multiple devices.

The key to being able to make effective use of these devices lies in the interconnect schemes. In the ispMACH 4A architecture, the macrocells are flexibly coupled to the product terms through the logic allocator, and the I/O pins are flexibly coupled to the macrocells due to the output switch matrix. In addition, more input routing options are provided by the input switch matrix. These resources provide the flexibility needed to fit designs efficiently.



17466G-001

Figure 1. ispMACH 4A Block Diagram and PAL Block Structure

Notes:

1. 16 for ispMACH 4A devices with 1:1 macrocell-I/O cell ratio (see next page).
2. Block clocks do not go to I/O cells in M4A(3,5)-32/32.
3. M4A(3,5)-192, M4A(3,5)-256, M4A3-384, and M4A3-512 have dedicated clock pins which cannot be used as inputs and do not connect to the central switch matrix.

Table 4. Architectural Summary of ispMACH 4A devices

	ispMACH 4A Devices	
		M4A3-64/32, M4A5-64/32 M4A3-96/48, M4A5-96/48 M4A3-128/64, M4A5-128/64 M4A3-192/96, M4A5-192/96 M4A3-256/128, M4A5-256/128 M4A3-384 M4A3-512
Macrocell-I/O Cell Ratio	2:1	1:1
Input Switch Matrix	Yes	Yes ¹
Input Registers	Yes	No
Central Switch Matrix	Yes	Yes
Output Switch Matrix	Yes	Yes

The Macrocell-I/O cell ratio is defined as the number of macrocells versus the number of I/O cells internally in a PAL block (Table 4).

The central switch matrix takes all dedicated inputs and signals from the input switch matrices and routes them as needed to the PAL blocks. Feedback signals that return to the same PAL block still must go through the central switch matrix. This mechanism ensures that PAL blocks in ispMACH 4A devices communicate with each other with consistent, predictable delays.

The central switch matrix makes a ispMACH 4A device more advanced than simply several PAL devices on a single chip. It allows the designer to think of the device not as a collection of blocks, but as a single programmable device; the software partitions the design into PAL blocks through the central switch matrix so that the designer does not have to be concerned with the internal architecture of the device.

Each PAL block consists of:

- ◆ Product-term array
- ◆ Logic allocator
- ◆ Macrocells
- ◆ Output switch matrix
- ◆ I/O cells
- ◆ Input switch matrix
- ◆ Clock generator

Notes:

1. M4A3-64/64 internal switch matrix functionality embedded in central switch matrix.

Product-Term Array

The product-term array consists of a number of product terms that form the basis of the logic being implemented. The inputs to the AND gates come from the central switch matrix (Table 5), and are provided in both true and complement forms for efficient logic implementation.

Table 5. PAL Block Inputs

Device	Number of Inputs to PAL Block
M4A3-32/32 and M4A5-32/32	33
M4A3-64/32 and M4A5-64/32	33
M4A3-64/64	33
M4A3-96/48 and M4A5-96/48	33
M4A3-128/64 and M4A5-128/64	33
M4A3-192/96 and M4A5-192/96	34
M4A3-256/128 and M4A5-256/128	34
M4A3-256/160 and M4A3-256/192	36
M4A3-384	36
M4A3-512	36

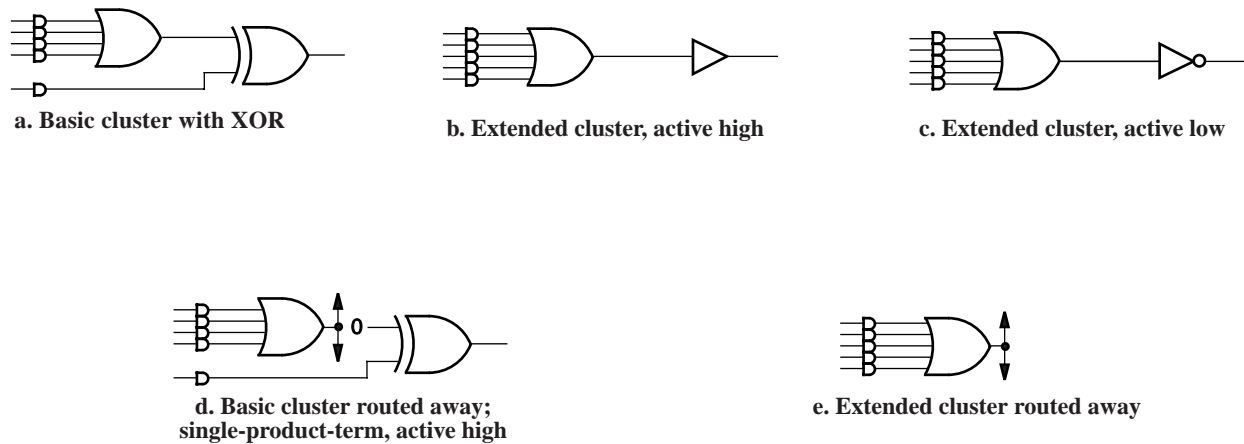
Logic Allocator

Within the logic allocator, product terms are allocated to macrocells in “product term clusters.” The availability and distribution of product term clusters are automatically considered by the software as it fits functions within a PAL block. The size of a product term cluster has been optimized to provide high utilization of product terms, making complex functions using many product terms possible. Yet when few product terms are used, there will be a minimal number of unused—or wasted—product terms left over. The product term clusters available to each macrocell within a PAL block are shown in Tables 6 and 7.

Each product term cluster is associated with a macrocell. The size of a cluster depends on the configuration of the associated macrocell. When the macrocell is used in synchronous mode (Figure 2a), the basic cluster has 4 product terms. When the associated macrocell is used in asynchronous mode (Figure 2b), the cluster has 2 product terms. Note that if the product term cluster is routed to a different macrocell, the allocator configuration is not determined by the mode of the macrocell actually being driven. The configuration is always set by the mode of the macrocell that the cluster will drive if not routed away, regardless of the actual routing.

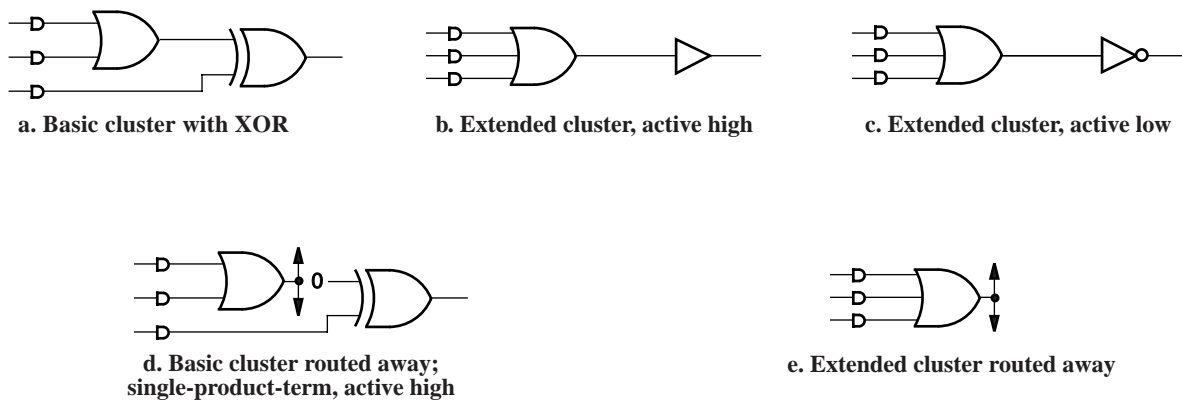
In addition, there is an extra product term that can either join the basic cluster to give an extended cluster, or drive the second input of an exclusive-OR gate in the signal path. If included with the basic cluster, this provides for up to 20 product terms on a synchronous function that uses four extended 5-product-term clusters. A similar asynchronous function can have up to 18 product terms.

When the extra product term is used to extend the cluster, the value of the second XOR input can be programmed as a 0 or a 1, giving polarity control. The possible configurations of the logic allocator are shown in Figures 3 and 4.



17466G-007

Figure 3. Logic Allocator Configurations: Synchronous Mode



17466G-008

Figure 4. Logic Allocator Configurations: Asynchronous Mode

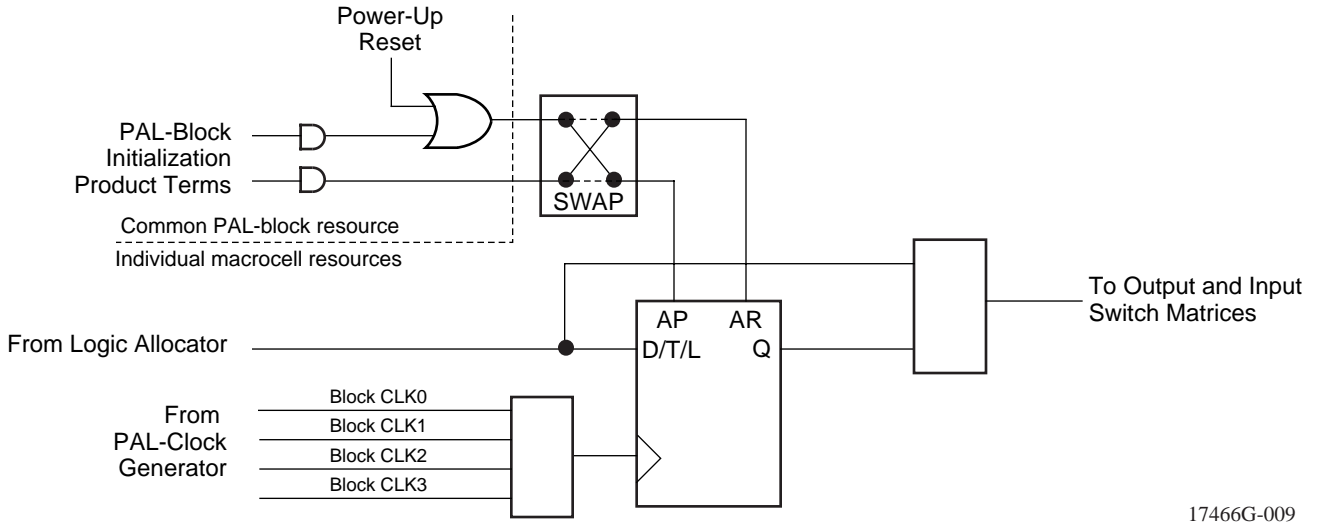
Note that the configuration of the logic allocator has absolutely no impact on the speed of the signal. All configurations have the same delay. This means that designers do not have to decide between optimizing resources or speed; both can be optimized.

If not used in the cluster, the extra product term can act in conjunction with the basic cluster to provide XOR logic for such functions as data comparison, or it can work with the D-,T-type flip-flop to provide for J-K, and S-R register operation. In addition, if the basic cluster is routed to another macrocell, the extra product term is still available for logic. In this case, the first XOR input will be a logic 0. This circuit has the flexibility to route product terms elsewhere without giving up the use of the macrocell.

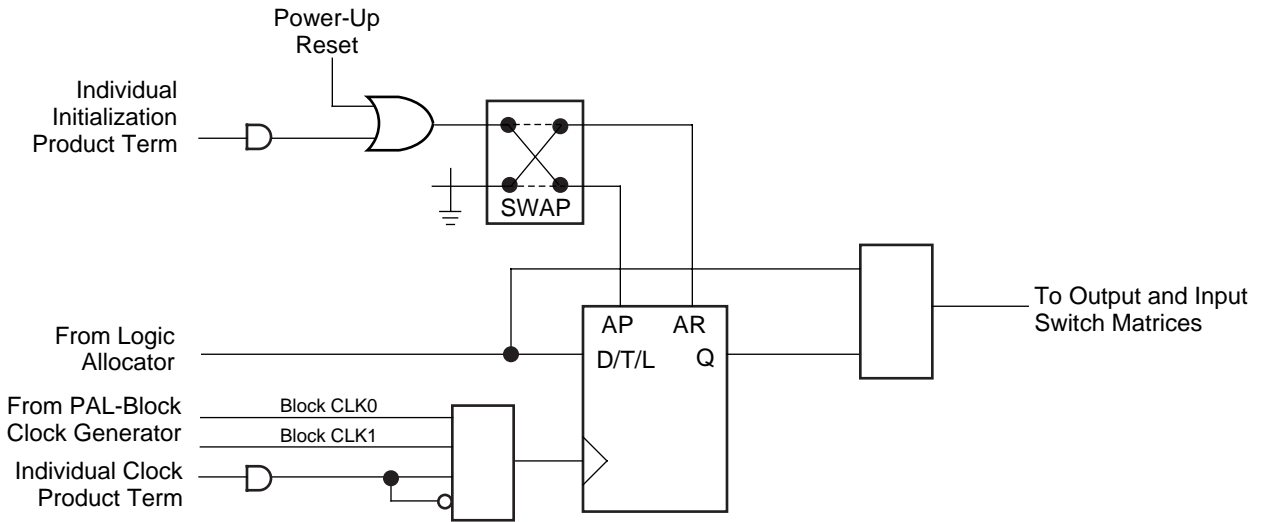
Product term clusters do not “wrap” around a PAL block. This means that the macrocells at the ends of the block have fewer product terms available.

Macrocell

The macrocell consists of a storage element, routing resources, a clock multiplexer, and initialization control. The macrocell has two fundamental modes: synchronous and asynchronous (Figure 5). The mode chosen only affects clocking and initialization in the macrocell.



a. Synchronous mode



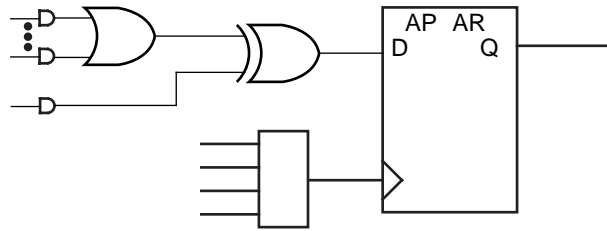
b. Asynchronous mode

17466G-010

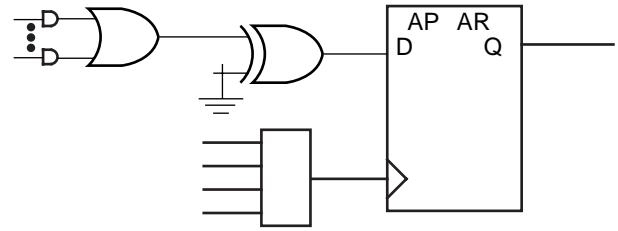
Figure 5. Macrocell

In either mode, a combinatorial path can be used. For combinatorial logic, the synchronous mode will generally be used, since it provides more product terms in the allocator.

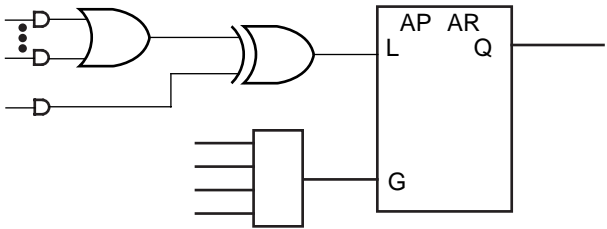
The flip-flop can be configured as a D-type or T-type latch. J-K or S-R registers can be synthesized. The primary flip-flop configurations are shown in Figure 6, although others are possible. Flip-flop functionality is defined in Table 8. Note that a J-K latch is inadvisable as it will cause oscillation if both J and K inputs are HIGH.



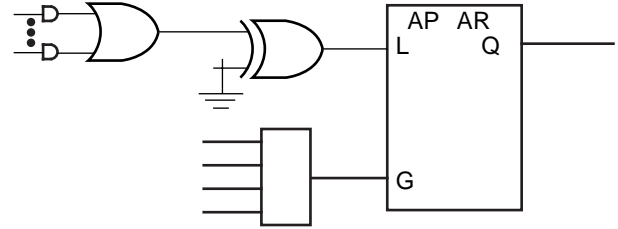
a. D-type with XOR



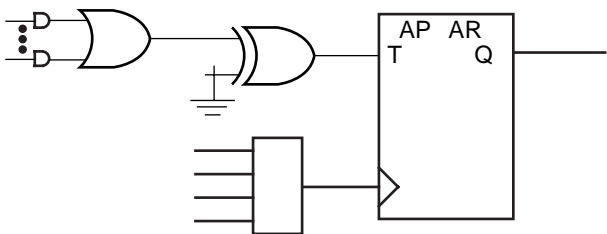
b. D-type with programmable D polarity



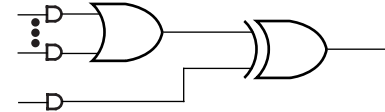
c. Latch with XOR



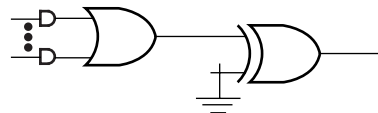
d. Latch with programmable D polarity



e. T-type with programmable T polarity



f. Combinatorial with XOR



g. Combinatorial with programmable polarity

Figure 6. Primary Macrocell Configurations

17466G-011

Table 8. Register/Latch Operation

Configuration	Input(s)	CLK/LE ¹	Q+
D-type Register	D=X	0, 1, ↓ (↑)	Q
	D=0	↑ (↓)	0
	D=1	↑ (↓)	1
T-type Register	T=X	0, 1, ↓ (↑)	Q
	T=0	↑ (↓)	Q
	T=1	↑ (↓)	\bar{Q}
D-type Latch	D=X	1 (0)	Q
	D=0	0 (1)	0
	D=1	0 (1)	1

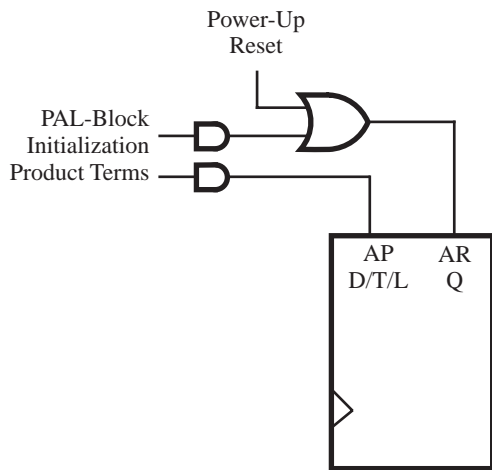
Note:

1. Polarity of CLK/LE can be programmed

Although the macrocell shows only one input to the register, the XOR gate in the logic allocator allows the D-, T-type register to emulate J-K, and S-R behavior. In this case, the available product terms are divided between J and K (or S and R). When configured as J-K, S-R, or T-type, the extra product term must be used on the XOR gate input for flip-flop emulation. In any register type, the polarity of the inputs can be programmed.

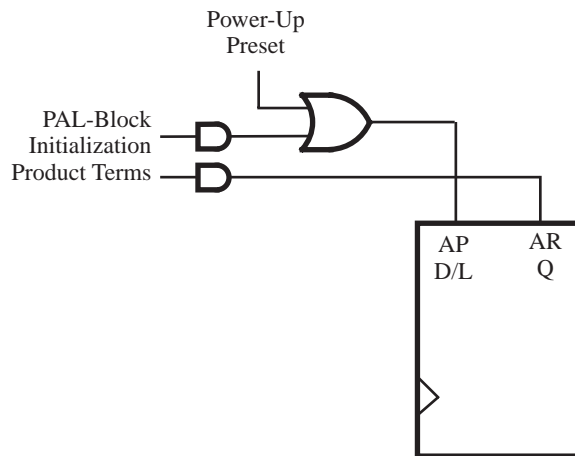
The clock input to the flip-flop can select any of the four PAL block clocks in synchronous mode, with the additional choice of either polarity of an individual product term clock in the asynchronous mode.

The initialization circuit depends on the mode. In synchronous mode (Figure 7), asynchronous reset and preset are provided, each driven by a product term common to the entire PAL block.



a. Power-up reset

17466G-012

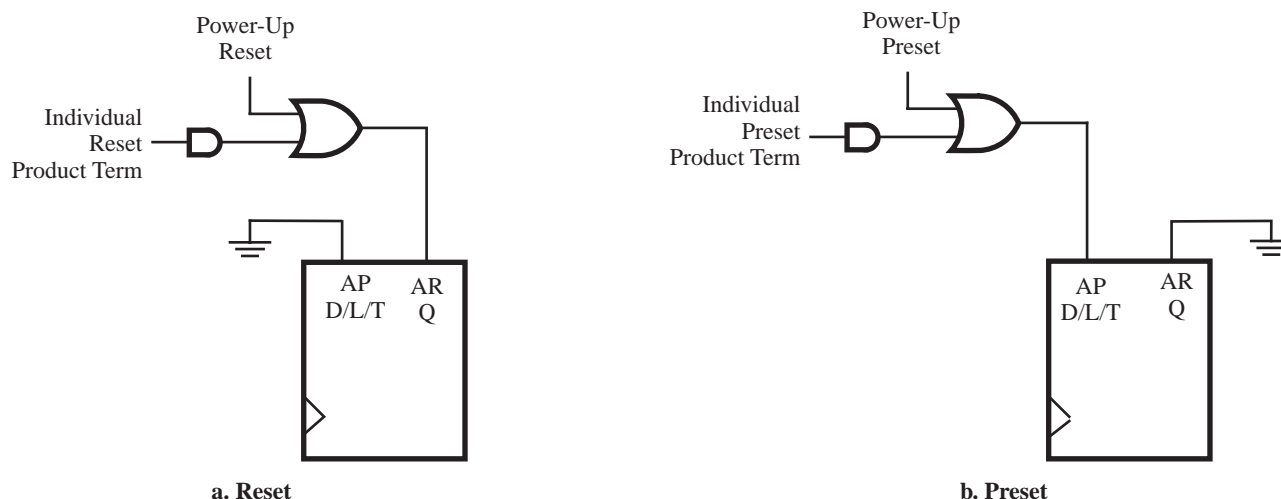


b. Power-up preset

17466G-013

Figure 7. Synchronous Mode Initialization Configurations

A reset/preset swapping feature in each macrocell allows for reset and preset to be exchanged, providing flexibility. In asynchronous mode (Figure 8), a single individual product term is provided for initialization. It can be selected to control reset or preset.



17466G-014

17466G-015

Figure 8. Asynchronous Mode Initialization Configurations

Note that the reset/preset swapping selection feature effects power-up reset as well. The initialization functionality of the flip-flops is illustrated in Table 9. The macrocell sends its data to the output switch matrix and the input switch matrix. The output switch matrix can route this data to an output if so desired. The input switch matrix can send the signal back to the central switch matrix as feedback.

Table 9. Asynchronous Reset/Preset Operation

AR	AP	CLK/LE ¹	Q+
0	0	X	See Table 8
0	1	X	1
1	0	X	0
1	1	X	0

Note:

- Transparent latch is unaffected by AR, AP

Input Switch Matrix

The input switch matrix (Figures 12 and 13) optimizes routing of inputs to the central switch matrix. Without the input switch matrix, each input and feedback signal has only one way to enter the central switch matrix. The input switch matrix provides additional ways for these signals to enter the central switch matrix.



17466G-002

Figure 12. ispMACH 4A with 2:1 Macrocell-I/O Cell Ratio - Input Switch Matrix



17466G-003

Figure 13. ispMACH 4A with 1:1 Macrocell-I/O Cell Ratio - Input Switch Matrix

IEEE 1149.1-COMPLIANT BOUNDARY SCAN TESTABILITY

All ispMACH 4A devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more complete board-level testing.

IEEE 1149.1-COMPLIANT IN-SYSTEM PROGRAMMING

Programming devices in-system provides a number of significant benefits including: rapid prototyping, lower inventory levels, higher quality, and the ability to make in-field modifications. All ispMACH 4A devices provide In-System Programming (ISP) capability through their Boundary Scan Test Access Ports. This capability has been implemented in a manner that ensures that the port remains compliant to the IEEE 1149.1 standard. By using IEEE 1149.1 as the communication interface through which ISP is achieved, customers get the benefit of a standard, well-defined interface.

ispMACH 4A devices can be programmed across the commercial temperature and voltage range. The PC-based ispVM™ software facilitates in-system programming of ispMACH 4A devices. ispVM takes the JEDEC file output produced by the design implementation software, along with information about the JTAG chain, and creates a set of vectors that are used to drive the JTAG chain. ispVM software can use these vectors to drive a JTAG chain via the parallel port of a PC. Alternatively, ispVM software can output files in formats understood by common automated test equipment. This equipment can then be used to program ispMACH 4A devices during the testing of a circuit board.

PCI COMPLIANT

ispMACH 4A devices in the -5/-55/-6/-65/-7/-10/-12 speed grades are compliant with the *PCI Local Bus Specification* version 2.1, published by the PCI Special Interest Group (SIG). The 5-V devices are fully PCI-compliant. The 3.3-V devices are mostly compliant but do not meet the PCI condition to clamp the inputs as they rise above V_{CC} because of their 5-V input tolerant feature.

SAFE FOR MIXED SUPPLY VOLTAGE SYSTEM DESIGNS

Both the 3.3-V and 5-V V_{CC} ispMACH 4A devices are safe for mixed supply voltage system designs. The 5-V devices will not overdrive 3.3-V devices above the output voltage of 3.3 V, while they accept inputs from other 3.3-V devices. The 3.3-V device will accept inputs up to 5.5 V. Both the 5-V and 3.3-V versions have the same high-speed performance and provide easy-to-use mixed-voltage design capability.

PULL UP OR BUS-FRIENDLY INPUTS AND I/Os

All ispMACH 4A devices have inputs and I/Os which feature the Bus-Friendly circuitry incorporating two inverters in series which loop back to the input. This double inversion weakly holds the input at its last driven logic state. While it is good design practice to tie unused pins to a known state, the Bus-Friendly input structure pulls pins away from the input threshold voltage where noise can cause high-frequency switching. At power-up, the Bus-Friendly latches are reset to a logic level "1." For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

All ispMACH 4A devices have a programmable bit that configures all inputs and I/Os with either pull-up or Bus-Friendly characteristics. If the device is configured in pull-up mode, all inputs and I/O pins are

weakly pulled up. For the circuit diagram, please refer to the document entitled *MACH Endurance Characteristics* on the Lattice Data Book CD-ROM or Lattice web site.

POWER MANAGEMENT

Each individual PAL block in ispMACH 4A devices features a programmable low-power mode, which results in power savings of up to 50%. The signal speed paths in the low-power PAL block will be slower than those in the non-low-power PAL block. This feature allows speed critical paths to run at maximum frequency while the rest of the signal paths operate in the low-power mode.

PROGRAMMABLE SLEW RATE

Each ispMACH 4A device I/O has an individually programmable output slew rate control bit. Each output can be individually configured for the higher speed transition (3 V/ns) or for the lower noise transition (1 V/ns). For high-speed designs with long, unterminated traces, the slow-slew rate will introduce fewer reflections, less noise, and keep ground bounce to a minimum. For designs with short traces or well terminated lines, the fast slew rate can be used to achieve the highest speed. The slew rate is adjusted independent of power.

POWER-UP RESET/SET

All flip-flops power up to a known state for predictable system initialization. If a macrocell is configured to SET on a signal from the control generator, then that macrocell will be SET during device power-up. If a macrocell is configured to RESET on a signal from the control generator or is not configured for set/reset, then that macrocell will RESET on power-up. To guarantee initialization values, the V_{CC} rise must be monotonic, and the clock must be inactive until the reset delay time has elapsed.

SECURITY BIT

A programmable security bit is provided on the ispMACH 4A devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit defeats readback of the programmed pattern by a device programmer, securing proprietary designs from competitors. Programming and verification are also defeated by the security bit. The bit can only be reset by erasing the entire device.

HOT SOCKETING

ispMACH 4A devices are well-suited for those applications that require hot socketing capability. Hot socketing a device requires that the device, when powered down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of the powered-down MACH devices be minimal on active signals.

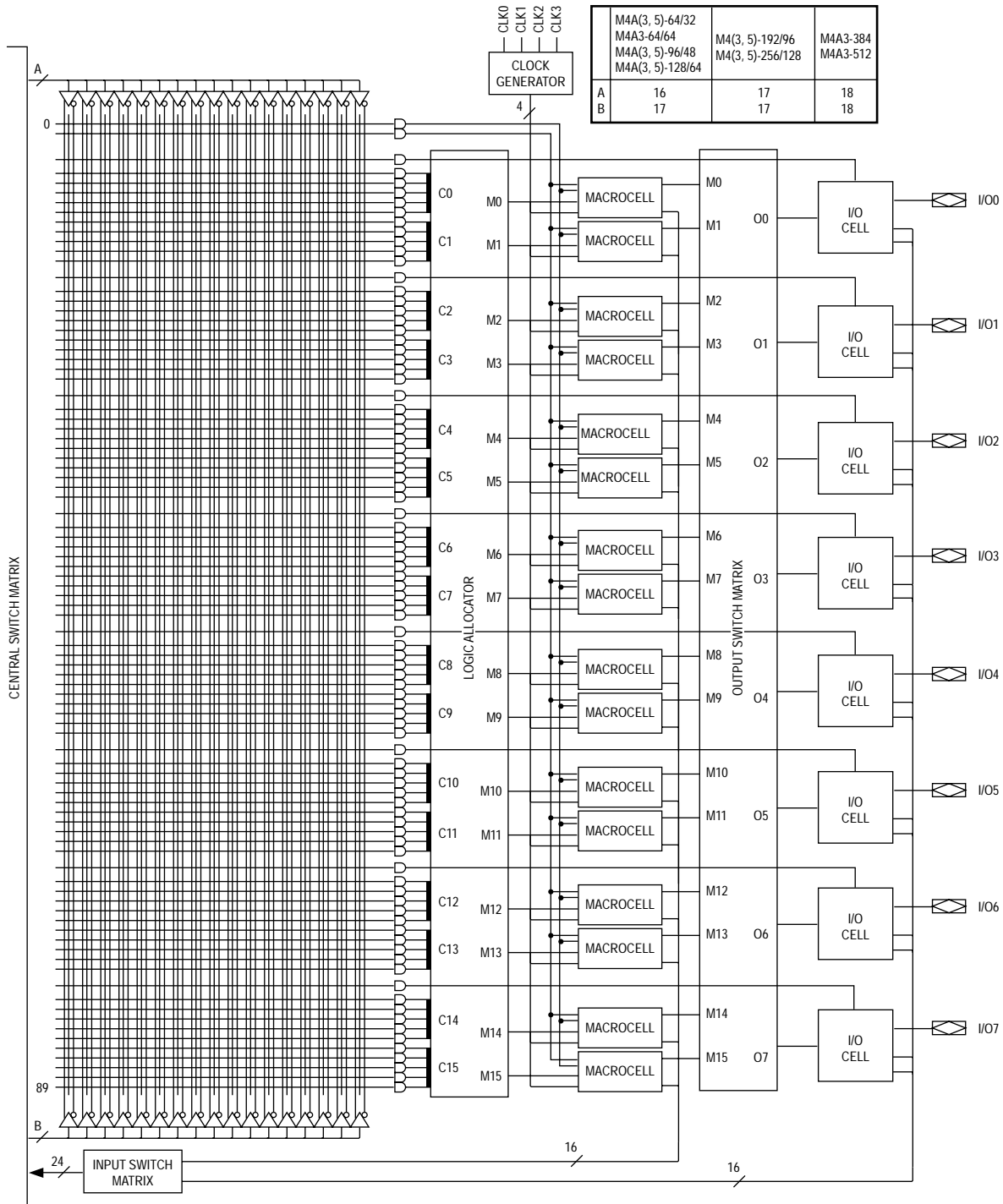
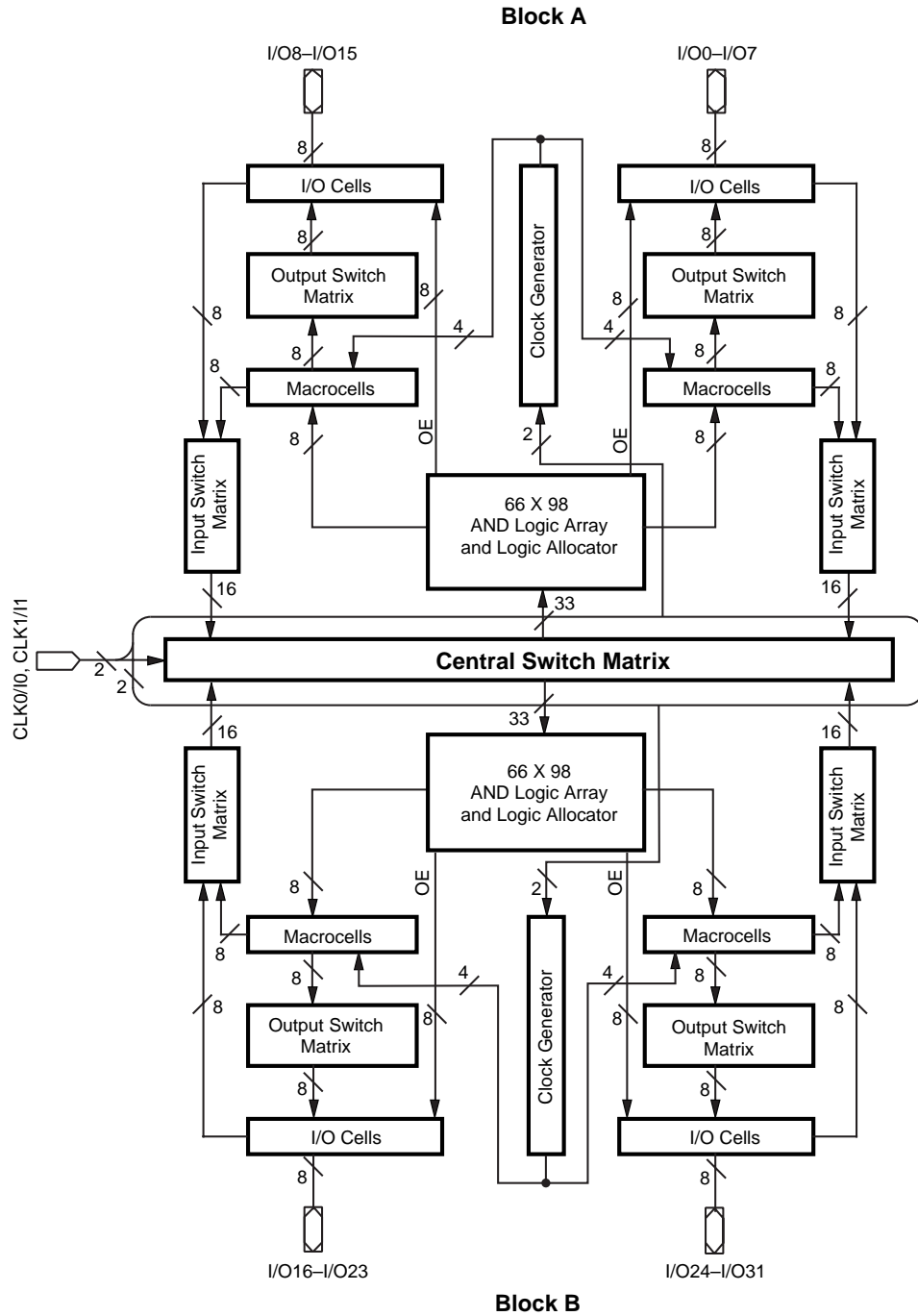
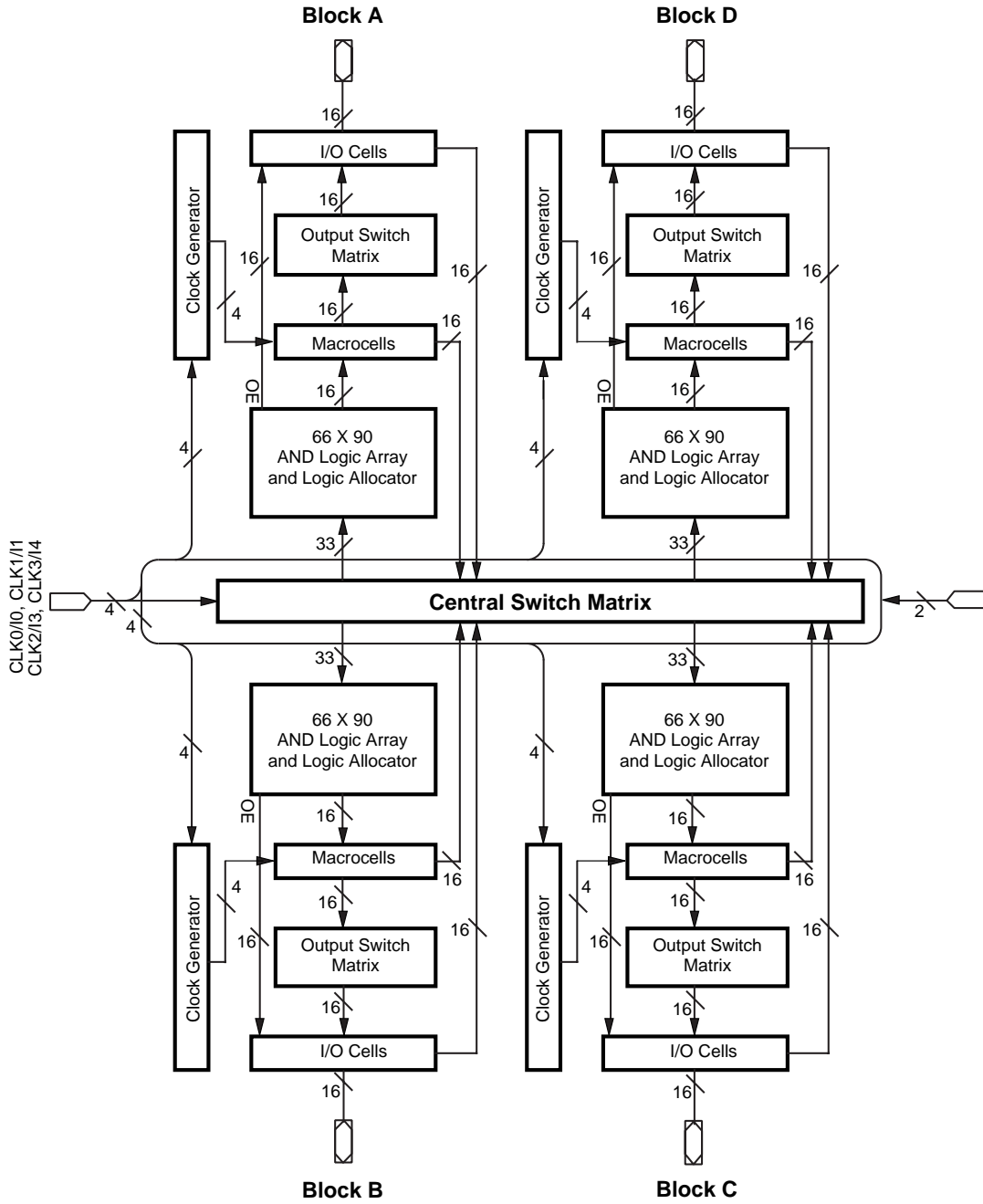


Figure 16. PAL Block for ispMACH 4A with 2:1 Macrocell - I/O Cell Ratio

BLOCK DIAGRAM – M4A(3,5)-32/32

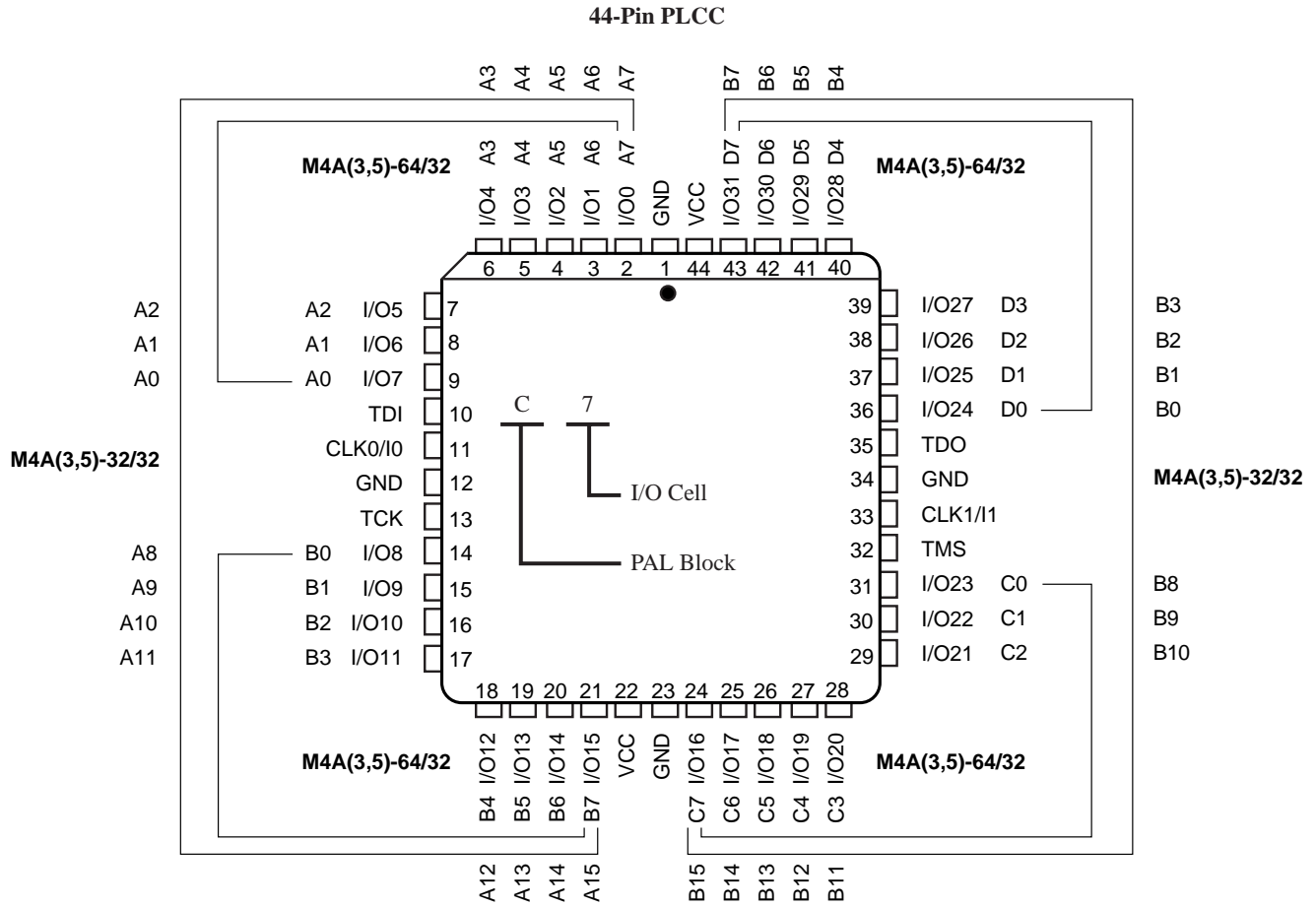


BLOCK DIAGRAM – M4A3-64/64



44-PIN PLCC CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View



PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

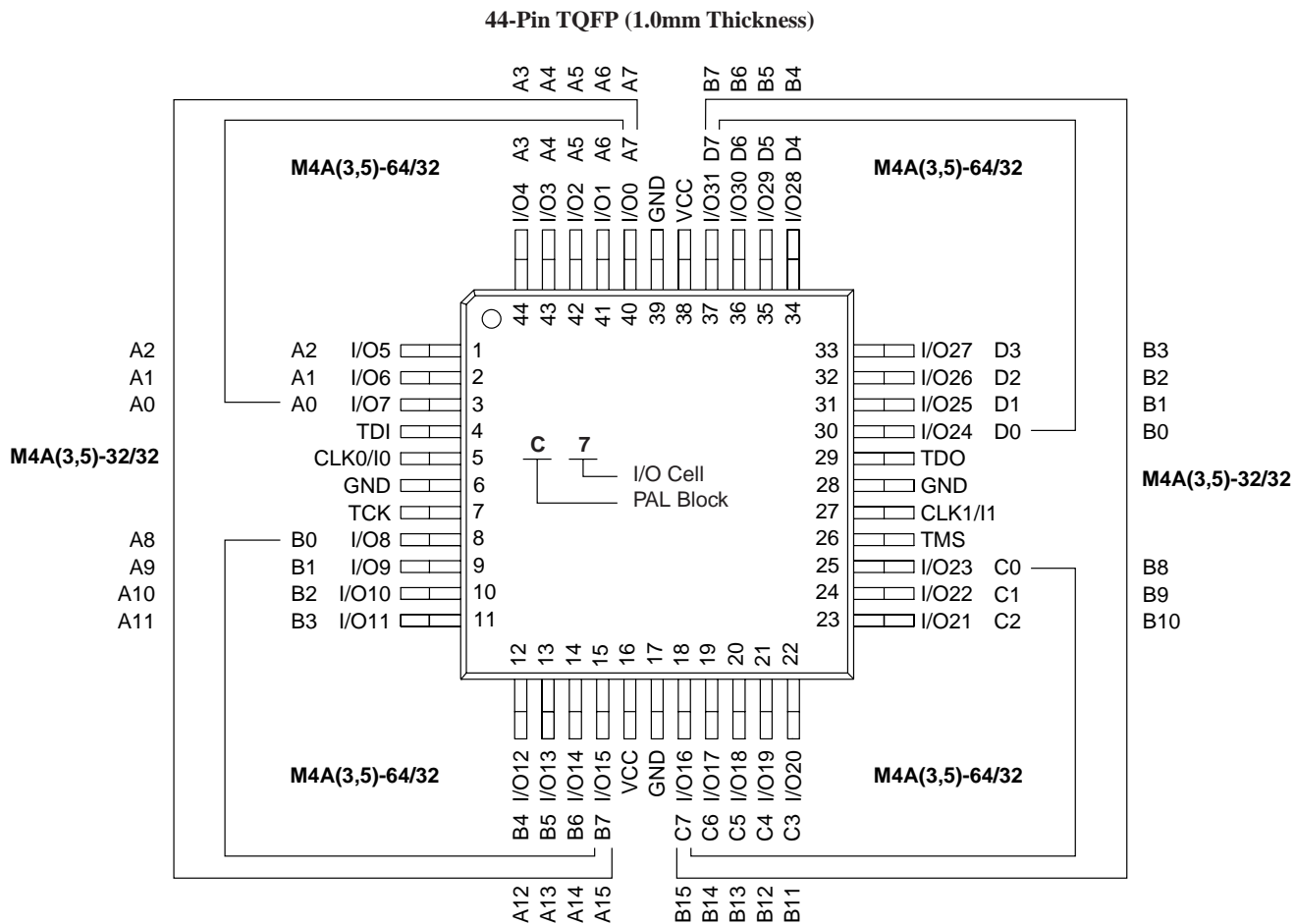
TCK = Test Clock

TMS = Test Mode Select

TDO = Test Data Out

44-PIN TQFP CONNECTION DIAGRAM (M4A(3,5)-32/32 AND M4A(3,5)-64/32)

Top View



PIN DESIGNATIONS

CLK/I = Clock or Input

GND = Ground

I/O = Input/Output

V_{CC} = Supply Voltage

TDI = Test Data In

TCK = Test Clock

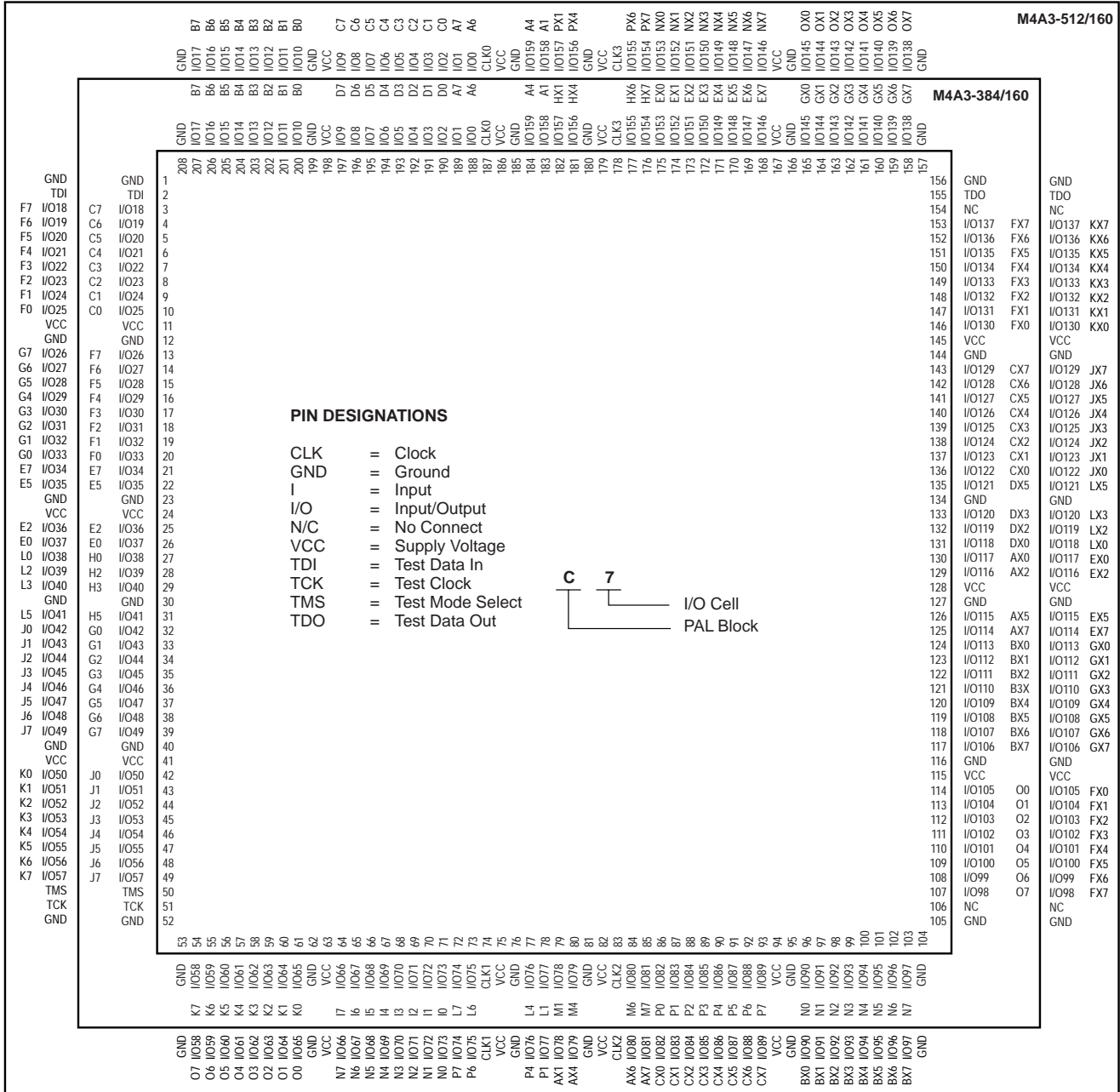
TMS = Test Mode Select

TDO = Test Data Out

208-PIN PQFP CONNECTION DIAGRAM (M4A3-384/160 AND M4A3-512/160)

Top View

208-Pin PQFP



17466Ga-044

256-BALL fpBGA CONNECTION DIAGRAM (M4A3-256/128)

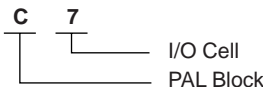
Bottom View

256-Ball fpBGA

	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	TRST	I/O117 O5	I/O116 O4	I/O113 O1	I/O126 P6	I/O124 P4	I12	NC	NC	NC	CLK0	I/O1 A1	I/O5 A5	I/O7 A7	I/O10 B2	I/O12 B4	A
B	I/O110 N6	I/O111 N7	I/O118 O6	I/O115 O3	I/O127 P7	I/O125 P5	I/O120 P0	NC	NC	NC	I1	I/O2 A2	I/O8 B0	I/O11 B3	I/O13 B5	NC	B
C	I/O108 N4	I/O109 N5	NC	I/O119 O7	I/O114 O2	I/O122 P2	I/O123 P3	NC	NC	I0	I/O4 A4	I/O6 A6	I/O15 B7	I/O14 B6	TDI	I/O23 C7	C
D	NC	I/O104 N0	TDO	GND	GND	VCC	GND	VCC	GND	GND	VCC	GND	VCC	I/O9 B1	I/O22 C6	I/O21 C5	D
E	I/O102 M6	NC	I/O107 N3	VCC	I/O105 N1	I/O106 N2	I13	CLK3	NC	NC	I/O0 A0	NC	GND	I/O20 C4	I/O19 C3	I/O31 D7	E
F	I/O98 M2	I/O103 M7	I/O101 M5	GND	I/O100 M4	I/O99 M3	I/O112 O0	I/O121 P1	NC	NC	I/O3 A3	I/O18 C2	VCC	I/O16 C0	I/O30 D6	I/O29 D5	F
G	NC	I/O96 M0	I11	VCC	NC	I/O97 M1	VCC	GND	GND	VCC	I/O17 C1	I/O28 D4	GND	I/O26 D2	I/O25 D1	I2	G
H	I/O88 L0	I10	I9	GND	I/O89 L1	I/O90 L2	GND	VCC	VCC	GND	I/O27 D3	I/O24 D0	VCC	NC	NC	NC	H
J	I/O91 L3	I/O92 L4	I/O93 L5	GND	I/O95 L7	I/O94 L6	GND	VCC	VCC	GND	I3	NC	GND	NC	NC	NC	J
K	NC	NC	NC	VCC	NC	NC	VCC	GND	GND	VCC	NC	NC	VCC	I4	NC	I/O32 E0	K
L	NC	NC	I/O80 K0	GND	I/O83 K3	NC	NC	NC	I/O59 H3	I/O61 H5	NC	NC	GND	I/O35 E3	I/O36 E4	I/O33 E1	L
M	I/O81 K1	I/O82 K2	I/O84 K4	GND	I/O67 I3	I/O65 I1	NC	NC	I/O58 H2	I/O48 G0	I/O51 G3	NC	VCC	I/O44 F4	I/O39 E7	I/O34 E2	M
N	I/O85 K5	I/O86 K6	ENABLE	VCC	GND	VCC	GND	VCC	GND	GND	VCC	GND	GND	TCK	I/O40 F0	I/O37 E5	N
P	I/O87 K7	I/O77 J5	I/O78 J6	I/O79 J7	I/O68 I4	I/O66 I2	NC	NC	NC	I6	I/O63 H7	I/O52 G4	I/O55 G7	TMS	I/O41 F1	I/O38 E6	P
R	I/O76 J4	I/O75 J3	I/O72 J0	I/O71 I7	I/O64 I0	I7	NC	NC	NC	I/O56 H0	I/O60 H4	I/O49 G1	I/O53 G5	I/O47 F7	I/O43 F3	I/O42 F2	R
T	I/O74 J2	I/O73 J1	I/O70 I6	I/O69 I5	I8	CLK2	NC	NC	CLK1	I5	I/O57 H1	I/O62 H6	I/O50 G2	I/O54 G6	I/O46 F6	I/O45 F5	T

PIN DESIGNATIONS

- CLK = Clock
- GND = Ground
- I = Input
- I/O = Input/Output
- N/C = No Connect
- VCC = Supply Voltage
- TDI = Test Data In
- TCK = Test Clock
- TMS = Test Mode Select
- TDO = Test Data Out
- TRST = Test Reset
- ENABLE = Program



m4a3.256.128_256bga

ispMACH 4A PRODUCT ORDERING INFORMATION

ispMACH 4A Devices Commercial and Industrial - 3.3V and 5V

Lattice programmable logic products are available with several ordering options. The order number (Valid Combination) is formed by a combination of:

	M4A3-	256 / 128	-7	Y	C										
<p>FAMILY TYPE</p> <p>M4A3- = ispMACH 4A Family Low Voltage Advanced Feature (3.3-V V_{CC})</p> <p>M4A5- = ispMACH 4A Family Advanced Feature (5-V V_{CC})</p> <p>MACROCELL DENSITY</p> <table border="0" style="width: 100%;"> <tr> <td>32 = 32 Macrocells</td> <td>192 = 192 Macrocells</td> </tr> <tr> <td>64 = 64 Macrocells</td> <td>256 = 256 Macrocells</td> </tr> <tr> <td>96 = 96 Macrocells</td> <td>384 = 384 Macrocells</td> </tr> <tr> <td>128 = 128 Macrocells</td> <td>512 = 512 Macrocells</td> </tr> </table> <p>I/Os</p> <p>/32 = 32 I/Os in 44-pin PLCC, 44-pin TQFP or 48-pin TQFP</p> <p>/48 = 48 I/Os in 100-pin TQFP</p> <p>/64 = 64 I/Os in 100-pin TQFP, 100-pin PQFP, or 100-ball caBGA</p> <p>/96 = 96 I/Os in 144-pin TQFP or 144-ball fpBGA</p> <p>/128 = 128 I/Os in 208-pin PQFP, 256-ball BGA or 256-ball fpBGA</p> <p>/160 = 160 I/Os in 208-pin PQFP</p> <p>/192 = 192 I/Os in 256-ball BGA or 256-ball fpBGA</p> <p>/256 = 256 I/Os in 388-ball fpBGA</p>	32 = 32 Macrocells	192 = 192 Macrocells	64 = 64 Macrocells	256 = 256 Macrocells	96 = 96 Macrocells	384 = 384 Macrocells	128 = 128 Macrocells	512 = 512 Macrocells							<p>OPERATING CONDITIONS</p> <p>C = Commercial (0°C to +70°C)</p> <p>I = Industrial (-40°C to +85°C)</p> <p>PACKAGE TYPE</p> <p>SA = Ball Grid Array (BGA)</p> <p>J = Plastic Leaded Chip Carrier (PLCC)</p> <p>JN = Lead-free Plastic Leaded Chip Carrier (PLCC)</p> <p>V = Thin Quad Flat Pack (TQFP)</p> <p>VN = Lead-free Thin Quad Flat Pack (TQFP)</p> <p>Y = Plastic Quad Flat Pack (PQFP)</p> <p>YN = Lead-free Plastic Quad Flat Pack (PQFP)</p> <p>FA = Fine-pitch Ball Grid Array (fpBGA)</p> <p>FAN = Lead-free Fine-pitch Ball Grid Array (fpBGA)</p> <p>CA = Chip-array Ball Grid Array (caBGA)</p> <p>SPEED</p> <p>-5 = 5.0 ns t_{PD}</p> <p>-55 = 5.5 ns t_{PD}</p> <p>-6 = 6.0 ns t_{PD}</p> <p>-65 = 6.5 ns t_{PD}</p> <p>-7 = 7.5 ns t_{PD}</p> <p>-10 = 10 ns t_{PD}</p> <p>-12 = 12 ns t_{PD}</p> <p>-14 = 14 ns t_{PD}</p>
32 = 32 Macrocells	192 = 192 Macrocells														
64 = 64 Macrocells	256 = 256 Macrocells														
96 = 96 Macrocells	384 = 384 Macrocells														
128 = 128 Macrocells	512 = 512 Macrocells														

*Package obsolete, contact factory.

Conventional Packaging

3.3V Commercial Combinations		
M4A3-32/32	-5, -7, -10	JC, VC, VC48
M4A3-64/32		JC, VC, VC48
M4A3-64/64		VC
M4A3-96/48	-55, -7, -10	VC
M4A3-128/64		YC, VC, CAC
M4A3-192/96	-6, -7, -10	VC, FAC
M4A3-256/128	-55, -65 ¹ , -7, -10	YC, FAC, SAC
M4A3-256/160		YC
M4A3-256/192	-7, -10	FAC
M4A3-384/160		YC
M4A3-384/192	-65, -10, -12	SAC, FAC
M4A3-512/160		YC
M4A3-512/192	-7, -10, -12	FAC
M4A3-512/256		FAC

3.3V Industrial Combinations		
M4A3-32/32		JI, VI, VI48
M4A3-64/32		JI, VI, VI48
M4A3-64/64		VI
M4A3-96/48	-7, -10, -12	VI
M4A3-128/64		YI, VI, CAI
M4A3-192/96		VI, FAI
M4A3-256/128		YI, FAI, SAI
M4A3-256/160		YI
M4A3-256/192	-10, -12	FAI
M4A3-384/160		YI
M4A3-384/192		FAI
M4A3-512/160	-10, -12, -14	YI
M4A3-512/192		FAI
M4A3-512/256		FAI

1. Use 5.5ns for new designs.